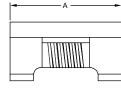
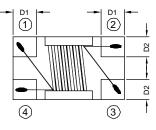
### WAQ7F SERIES

#### 1. PART NO. EXPRESSION :

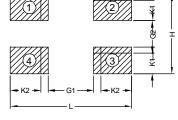
<u>WAQ 7 F 510 - R B - 10</u> (a) (b)(c) (d) (e)(f) (g) (a) Series code (b) Dimension code (c) Material code (d) Inductance code : 510 = 51 uH (e) R : Tape & Reel (f) Rated Current : B = 200mA (g) 10 : Internal Control Number

### 2. CONFIGURATION & DIMENSIONS :









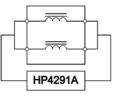
PCB Pattern

PC board should be designed so that products are not sufficient under mechanical stress as warping the board. Products shall be positioned in the sideway direction against the mechanical stress to prevent failure.

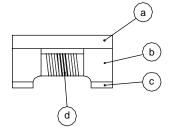
А	В	С	D1	D2	L	н	K1	K2	G1	G2	-ti
4.5±0.2	3.2±0.2	2.8±0.2	1.0±0.1	1.2±0.1	5.2	3.6	0.85	0.7	3	0.9	fide

#### 3. SCHEMATIC :

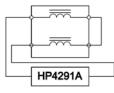
#### Common mode



#### 4. MATERIALS :



#### Differential mode



(a) Upper Plate:Ferrite

- (b) Core: Ferrite Core
- (c) Termination : Tin (Pb Free)

(d) Wire : Enameled Copper Wire

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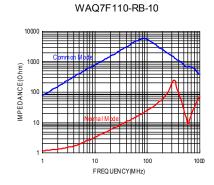
#### 5. GENERAL SPECIFICATION :

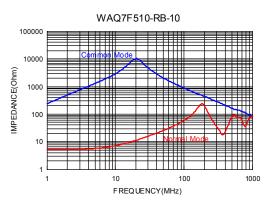
- a) Test Frequency: Inductance:100KHz/0.1V; Impedance:10MHz/0.1V
- b) Operating temperature: -40  $^\circ\!\mathrm{C}$  ~+125  $^\circ\!\mathrm{C}$
- c) Storage Temperature:-40℃ ~ +125℃
- d) All test data is referenced to  $25^\circ\!\mathrm{C}$  ambient.
- e) Indicate Compliant to AEC-Q200 and PPAP level4 eligibility

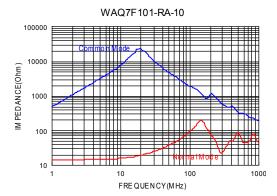
#### 6. ELECTRICAL CHARACTERISTICS :

Part No.	Common mode Inductance ( uH )	DCR (Ω) Max.	Rated Current (mA)	Rated Voltage ( Vdc )	IR (Ω) Min.
WAQ7F110-RB-10	11+50/-30%	0.8	200	50	10M
WAQ7F510-RB-10	51+50/-30%	1.0	200	50	10M
WAQ7F101-RA-10	100+50/-30%	2.0	100	50	10M

#### 7. CHARACTERISTICS CURVES :







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### 8. RELIABILITY & TEST CONDITION :

ITEM	PERFORMANCE	TEST CONDITION		
Electrical Characteristics Tes	st			
Z (common mode)		Agilent-4291A+ Agilent-16197A		
DCR	Refer to standard electrical characteristics list	Agilent-4338B		
I.R.		Agilent4339		
Temperature Rise Test	Rated Current < 1A ΔT 20°CMax	1. Applied the allowed DC current.		
	Rated Current $\geq$ 1A $\Delta$ T 40°CMax	2. Temperature measured by digital surface thermometer.		
Mechanical Performance Tes	st			
Solderability Test	More than 90% of termincal electrode should be covered with solder.	Preheat: 150°C ,60sec.。 Solder: Sn99.5%-Cu0.5%。 Temperature: 245±5°C。 Flux for lead free: Rosin.9.5%。 Dip time: 4±1sec。 Depth: completely cover the termination		
Solder Heat Resistance	Appearance: No damage. Inductance: within±10% of initial value	Solder tamperature: 260± 5° C Temperature ramp/immersion and immersion rate: 25± 6 mm/s Dip time: 10± 1sec. Number of heat cycles:1 Depth: completely cover the termination. Preconditioning : Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles) With the component mounted on a PCB with the device to be tested, apply a force (>0805:1kg, <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.		
Terminal Strength	RDC: within ±15% of initial value and shall not exceed the specification value			
		substrate press tool shear force		



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#### 8. RELIABILITY & TEST CONDITION :

ITEM	PERFORMANCE		TEST CONDI	TION	
Reliabilty Test					
Life Test		Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature : 85±2° C Applied Current : rated current Duration : 1000±12hrs Measured at room temperature after placing for 24±2 hrs.			
Thermal Shock	Appearance: No damage.	Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles)			
The mar brook	Inductance: within±10% of initial value	Step	Temperature (° C)	Times (min.)	
	RDC: within ±15% of initial value and shall not	1	-40±2	30±5	
	exceed the specification value	2	25±2	≦ 0.5	
		3	105±2	30±5	
				3013	
		Number of cycles: 500 Measured at room fempraturc after placing for 24±2 hrs			
Humidity Resistance Test		(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature : 85±2° C Humidity : 85±2% R.H Duration: 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs			
Vibration Test		Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles)			
		Oscillation F Equipment : Total Amplitu	requency : 10~2K~10 Vibration checker ude : 1.52mm± 10% 9 : 12 hours(20 minutes	Hz for 20 minutes	
				, 12 cycles each of 3	



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## 9. SOLDERING AND MOUNTING :

#### 9-1. Soldering

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all wave and re-flow soldering systems.

If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

#### 9-1.1 Solder Re-flow :

Recommended temperature profiles for re-flow soldering in Figure 1.

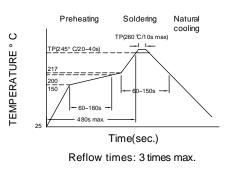
#### 9-1.2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

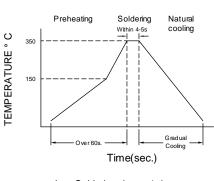
- Note : a) Preheat circuit and products to 150° C.
  - b) 355° C tip temperature (max)
- d) 1.0mm tip diameter (max)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm

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- c) Never contact the ceramic with the iron tip f)
- f) Limit soldering time to 4-5 secs.





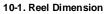


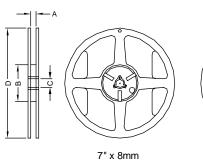
Iron Soldering times: 1 times max. Fig.2

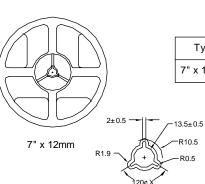


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### 10. PACKAGING INFORMATION :

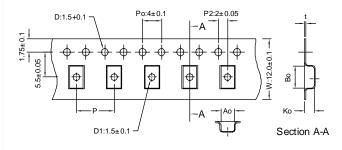






Туре	A(mm)	B(mm)	C(mm)	D(mm)
7" x 12mm	13.5±0.5	60.0±2.0	13.5±0.5	178.0±2.0

#### 10-2 Tape Dimension / 12mm



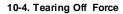
Series	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
WAQ7F	4.90±0.1	3.60±0.1	3.00±0.1	8.0±0.1	0.26± 0.05

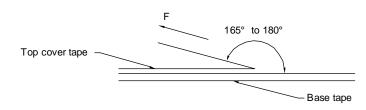
#### 10-3. Packing Quantity

Series	WAQ7F		
Chip / Reel	500		
Inner Box	2500		
Middle Box	12500		
Carton	25000		



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The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed
(° C)	(%)	(hPa)	(mm/min)
5~35	45~85	860~1060	

### **Application Notice**

- 1. Storage Conditions :
  - To maintain the solderability of terminal electrodes :
    - a) Temperature and humidity conditions : Less than 40° C and 60% RH.
    - b) Recommended products should be used within 12 months from the time of delivery.
    - c) The packaging material should be kept where no chlorine or sulfur exists in the air.

#### 2. Transportation :

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) The use of tweezers or vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

